

Surface Mount Schottky Barrier Rectifier
Reverse Voltage - 20 to 200 V Forward Current - 2.0A

Features

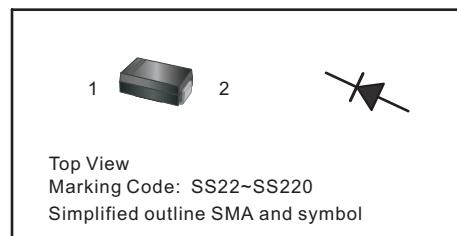
- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

MECHANICAL DATA

- Case: SMA
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 60mg / 0.0021oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SS22G	SS24G	SS26G	SS28G	SS210G	SS212G	SS215G	SS220G	Units		
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	20	40	60	80	100	120	150	200	V		
Maximum RMS voltage	V _{RMS}	14	28	42	56	70	84	105	140	V		
Maximum DC Blocking Voltage	V _{DC}	20	40	60	80	100	120	150	200	V		
Maximum Average Forward Rectified Current	I _{F(AV)}	2.0							A			
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	50				40				A		
Max Instantaneous Forward Voltage at 2 A	V _F	0.55		0.70		0.85		0.95		V		
Maximum DC Reverse Current T _a = 25°C at Rated DC Reverse Voltage T _a = 100°C	I _R	0.5 5		0.3 3						mA		
Typical Junction Capacitance ⁽¹⁾	C _j	220		80						pF		
Typical Thermal Resistance ⁽²⁾	R _{θJA}	80							°C/W			
Operating Junction Temperature Range	T _j	-55 ~ +125							°C			
Storage Temperature Range	T _{stg}	-55 ~ +150							°C			

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.



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SS22G THRU SS220G

Fig.1 Forward Current Derating Curve

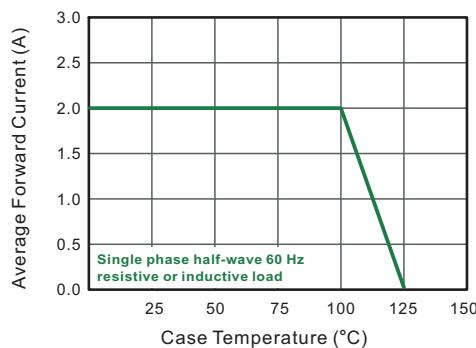


Fig.3 Typical Forward Characteristic

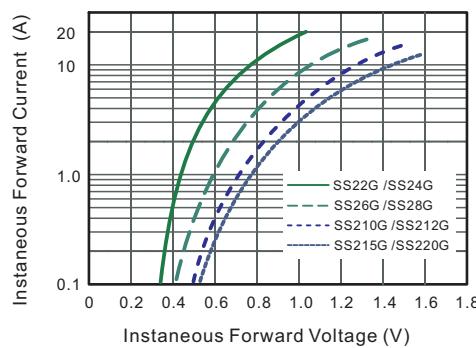


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

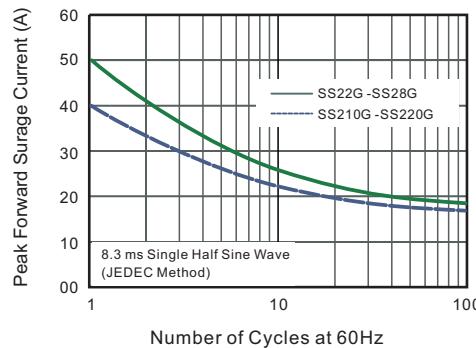


Fig.2 Typical Reverse Characteristics

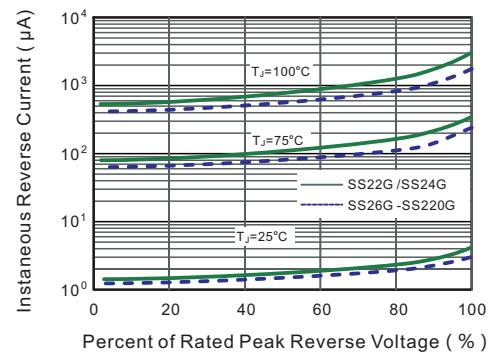


Fig.4 Typical Junction Capacitance

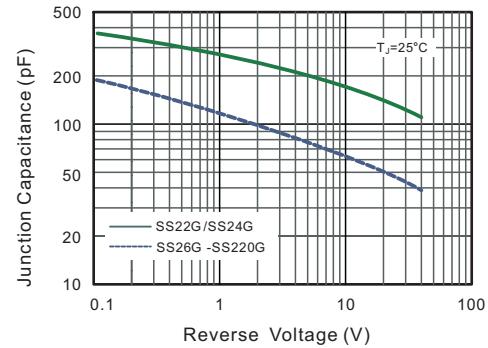
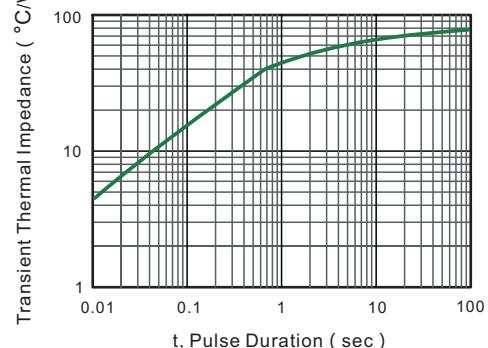


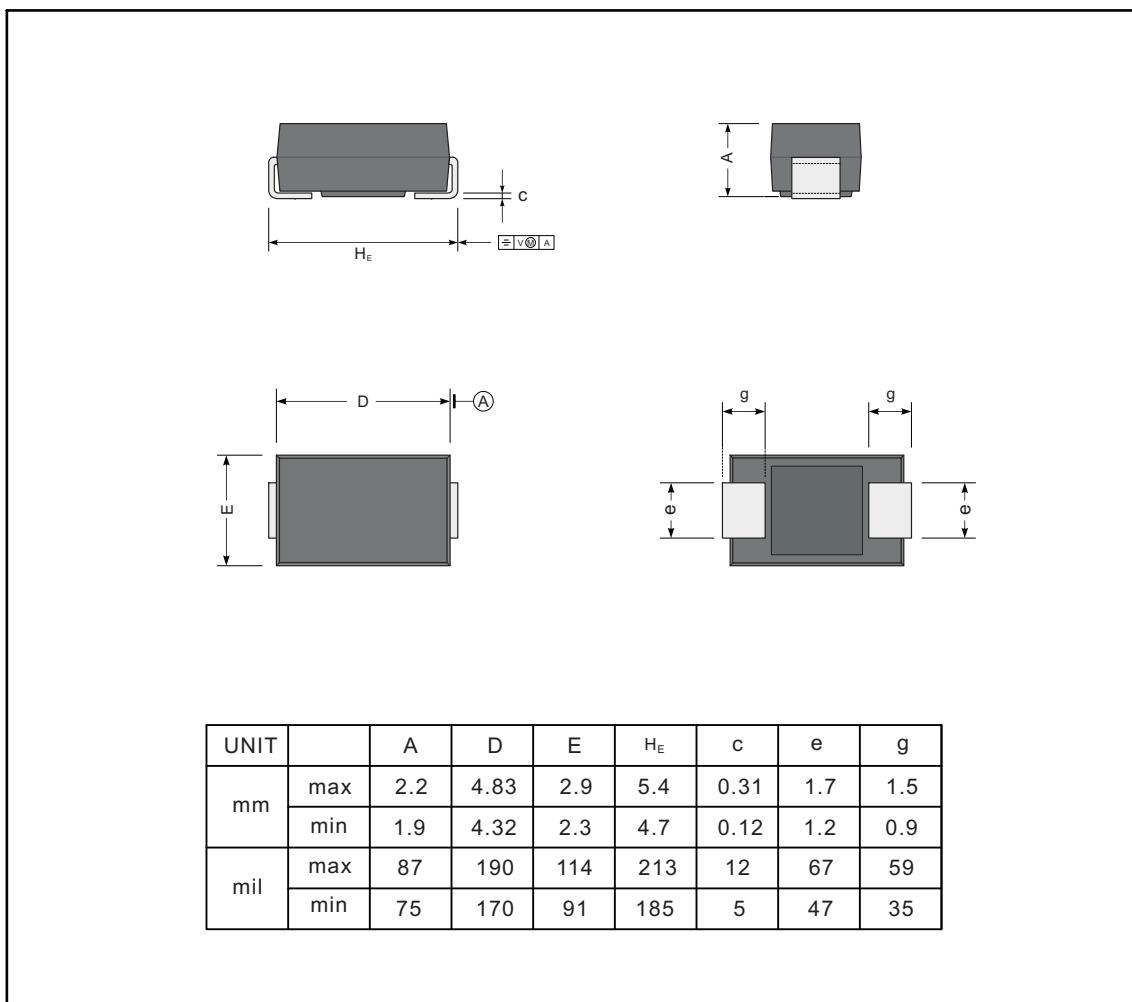
Fig.6- Typical Transient Thermal Impedance



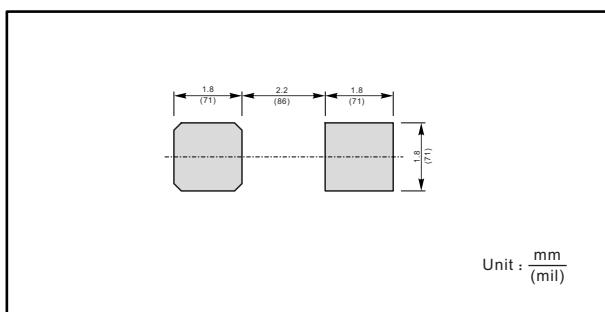
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMA



The recommended mounting pad size



Marking

Type number	Marking code
SS22G	SS22
SS24G	SS24
SS26G	SS26
SS28G	SS28
SS210G	SS210
SS212G	SS212
SS215G	SS215
SS220G	SS220